









CET0215

150V ▲ 360mΩ ▲ 2A ▲ Si MOSFET

SILICON Si MOSFET ▲ SMD type

N-channel enhancement mode

UL94V-0 rated flame retardant epoxy

SOT223 package ▲ MSL 3

Super high dense cell density for extremely low R_{DS(ON)}

Rugged and reliable

MAXIMUM RATINGS

Parameter (T _A = 25°C, unless otherwise noted)	Characteristics	
Drain-Source Voltage	V _{DS}	150V
Gate-Source Voltage	V _{GS}	±20V
Continuous Drain Current	I _D	2A
Pulsed Drain Current Note 1	I _{DM}	8A
Maximum Power Dissipation	P _D	3W
Operating and Storage Temperature Range	T _J , T _{STG}	-55°C to +150°C

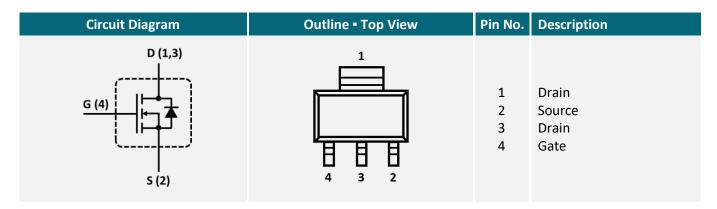
THERMAL CHARACTERISTICS

Parameter	Symbol	Limit
Thermal Resistance, Junction-to-Case Note 2	R _{TH_JC}	42°C/W

APPLICATIONS

Audio	Industrial	Power over	Power	UPS
Amplifier	Control	Ethernet	Inverter	
((PoE		

PIN DESCRIPTION





ELECTRICAL CHARACTERISTICS ▲ T_A = 25°C, unless otherwise noted

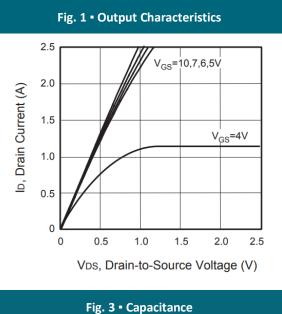
Item	Condition	Symbol	Min.	Тур.	Max.	Unit		
Off Characteristics								
Drain-Source Breakdown Voltage	$V_{GS} = 0V$, $I_{D} = 250\mu A$	BV_{DSS}	150			V		
Zero Gate Voltage Drain Current	$V_{DS} = 150V, V_{GS} = 0V$	I _{DSS}			1	μΑ		
Gate Body Leakage Current, Forward	$V_{GS} = 20V, V_{DS} = 0V$	I _{GSSF}			100	nA		
Gate Body Leakage Current, Reverse	$V_{GS} = -20V, V_{DS} = 0V$	I_{GSSR}			-100	nA		
On Characteristics Note 3								
Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	$V_{GS(th)}$	2		4	V		
Static Drain-Source On-Resistance	$V_{GS} = 10V, I_D = 2A$	R _{DS(ON)}		360	440	mΩ		
Static Drain-Source On-Resistance	$V_{GS} = 6V$, $I_D = 2A$	R _{DS(ON)}		480	580	mΩ		
Dynamic Characteristics Note 4								
Input Capacitance	$V_{DS} = 25V$, $V_{GS} = 0V$, $f = 1MHz$	C _{ISS}		385		pF		
Output Capacitance	$V_{DS} = 25V$, $V_{GS} = 0V$, $f = 1MHz$	Coss		85		pF		
Reverse Transfer Capacitance	$V_{DS} = 25V$, $V_{GS} = 0V$, $f = 1MHz$	C_{RSS}		25		pF		
Switching Characteristics Note 4								
Turn-On Delay Time	$V_{DD} = 50V$, $V_{GS} = 10V$, $I_D = 1A$, $R_{G(ext)} = 22\Omega$	t _{D(ON)}		11	22	ns		
Turn-On Rise Time	V_{DD} = 50V, V_{GS} = 10V, I_D = 1A, $R_{G(ext)}$ = 22 Ω	t _R		3	6	ns		
Turn-Off Delay Time	V_{DD} = 50V, V_{GS} = 10V, I_D = 1A, $R_{G(ext)}$ = 22 Ω	t _{D(OFF)}		33	66	ns		
Turn-Off Fall Time	V_{DD} = 50V, V_{GS} = 10V, I_{D} = 1A, $R_{G(ext)}$ = 22 Ω	t _F		6	12	ns		
Total Gate Charge	V_{DS} = 80V, V_{GS} = 10V, I_{D} = 1.8A	Q_{G}		9.2	12	nC		
Gate Source Charge	$V_{DS} = 80V$, $V_{GS} = 10V$, $I_D = 1.8A$	Q_{GS}		1.5		nC		
Gate Drain Charge	$V_{DS} = 80V$, $V_{GS} = 10V$, $I_{D} = 1.8A$	Q_{GD}		2.7		nC		
Drain-Source Diode Characteristics a	nd Maximum Ratings							
Drain-Source Diode Forward Current Note 3		Is			1.85	Α		
Drain-Source Diode Forward Voltage Note 3	V _{GS} = 0V, I _S = 1.85A	V_{SD}			1.2	V		

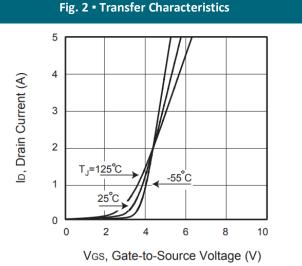
Notes

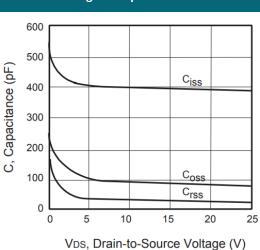
- 1: Repetitive Rating: Pulse width limited by maximum junction temperature
- 2: Surface Mounted on FR4 Board, t ≤ 10 sec
- 3: Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4: Guaranteed by design, not subject to production testing.

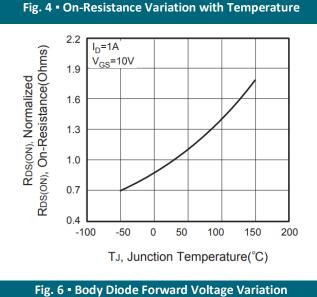


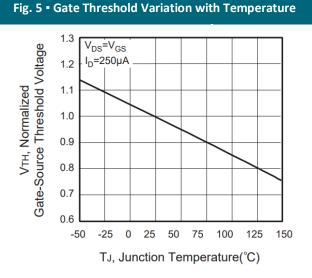
REFERENCE DATA A TYPICAL DEVICE PERFORMANCE

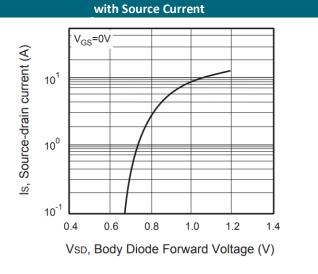










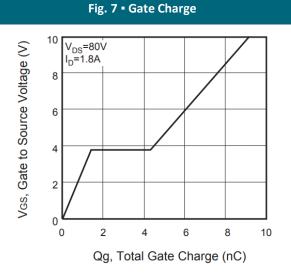


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10³



REFERENCE DATA A TYPICAL DEVICE PERFORMANCE



10¹ R_{DS(ON)}Limit 10ms 100ms 10 DC

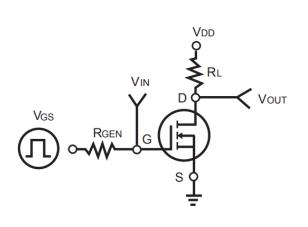
Fig. 8 • Maximum Safe Operating Area

VDS, Drain-Source Voltage (V)

Fig. 9 - Switching Test Circuit



T_C=25°C T_J=150°C Single Pulse



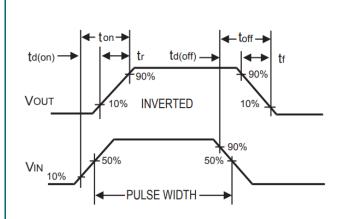
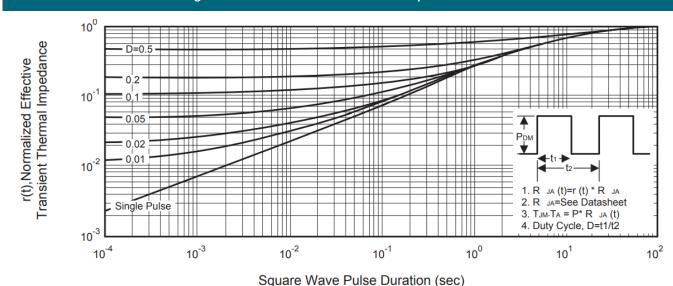


Fig. 11 - Normalized Thermal Transient Impedance Curve

lb, Drain Current (A)

10⁻²

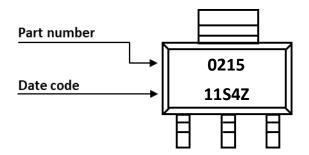
10⁰



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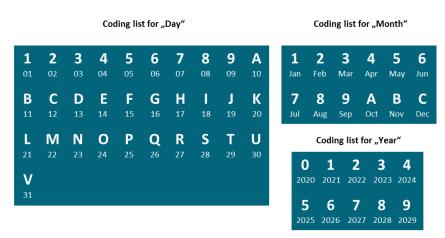
PART MARKING



DATE CODE

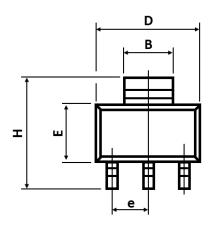
Example: 11S4Z

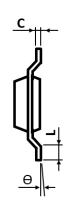


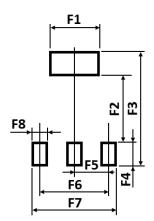


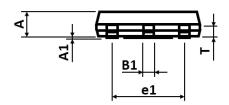


PACKAGE OUTLINE AND RECOMMENDED PAD LAYOUT









Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
Α	1.500	-	1.700
A1	0.020	-	0.100
В	2.950	-	3.200
B1	0.670	-	0.800
С	0.240	-	0.350
D	6.300	-	6.850
e		2 300 TYP	

Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
	4.600 TYP	
3.300	-	3.800
6.700	-	7.300
0.900	-	-
0.600	-	0.800
	10° MAX	
	3.300 6.700 0.900	(Min.) (Typ.) 4.600 TYP 3.300 - 6.700 - 0.900 - 0.600 -

Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
F1	-	3.500	-
F2	-	4.600	-
F3	-	8.000	
F4	-	1.600	

Sym	Millimeters (Min.)	Millimeters (Max.)	
F5	-	2.300	-
F6	-	4.600	-
F7	-	5.600	-
F8	-	1.200	-

Notes: 1. The suggested land pattern dimensions have been provided for reference only.

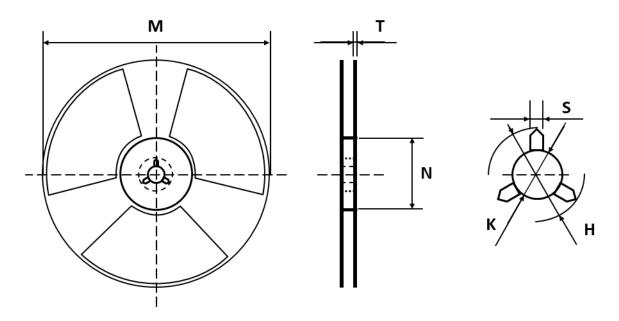
2. For further information, please reference document IPC-7351A.

ORDERING INFORMATION

Part Number	Package	Packing	Reel Qty.	Inner Box Qty.	Outer Box Qty.
CET0215	SOT223	7" Reel	2,500pcs	5,000pcs	15,000pcs

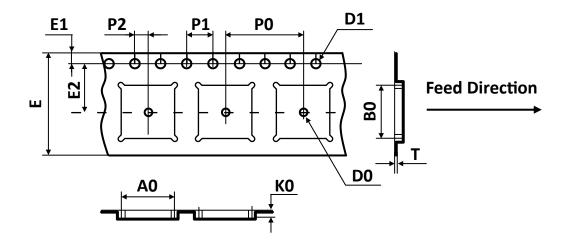


REEL DIMENSIONS ▲ All dimensions in mm



Tape Size	Reel Size	M	N	Т	Н	K	S
8mm	Ø180	Ø178.00	Ø54.00	1.20	20.00	13.30	3.00
	ATOU	±1.00	±0.50	±0.20	±1.00	±0.30	±1.00

TAPE DIMENSIONS ▲ All dimensions in mm

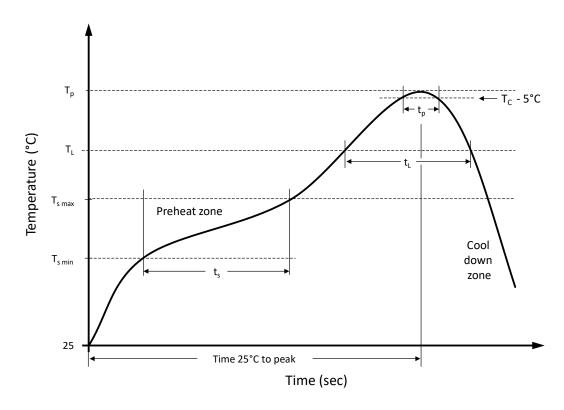


Package	Α0	В0	КО	D0	D1	E	E1	E2	P0	P1	P2	T
SOT223	2.40	2.60	1.20	1.00	1.50	8.00	1.75	3.50	4.00	4.00	2.00	0.20
SOT223	±0.10	±0.10	±0.10	±0.10	±0.10	±0.10	±0.10	±0.10	±0.10	±0.10	±0.05	±0.02

Note: All dimensions meet EIA-481-D requirements.



RECOMMENDED REFLOW SOLDERING PROFILE



Recommended reflow soldering conditions ▲ **Refer to JEDEC J-STD-020E**

Profile Features		Sn-Pb Eutetic Assembly	Pb-Free Assembly
Preheat temperature min.	$T_{s min}$	100 °C	150 °C
Preheat temperature max.	T _{s max}	150 °C	200 °C
Preheat time t _s from T _{s min} to T _{s max}	ts	120 seconds	120 seconds
Ramp-up rate (T₁ to Tp)		max. 3 °C/second	max. 3 °C/second
Liquidous temperature	T_L	183 °C	217 °C
Time t _L maintained above T _L	t _L	150 seconds max.	150 seconds max.
Peak package body temperature	Tp	235°C	260°C
Timeframe of within 5°C below and up to max actual peak body temperature	t _p	20 seconds max.	30 seconds max.
Ramp-down rate (T _L to T _p)		max. 6 °C/second	max. 6 °C/second
Time 25°C to peak temperature		max. 6 minutes	max. 8 minutes



REVISION TABLE

Revision	Date	Status	Notes
001	30/09/2022	Initial release	Initial publication

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